

Electronic Patent Application Fee Transmittal

Application Number:	10711503			
Filing Date:	22-Sep-2004			
Title of Invention:	IC PACKAGE HAVING GROUND IC CHIP AND METHOD OF MANUFACTURING SAME			
First Named Inventor:	PEI-HAW TSAO			
Filer:	James H. Ortega/Angela Young			
Attorney Docket Number:	TSMC 2003-1622			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	790	790
Total in USD (\$)				790